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(54) CHIP PACKAGING STRUCTURE AND METHOD FOR PACKAGING THE CHIP

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(57)ABSTRACT

A method for packaging a chip, the chip is packaged by disposing positioning post on the surface of the carrier, and the groove matching the positioning post is formed on the surface of the chip. During melting the first solder pastes and the second solder pastes, due to the interaction between the positioning post and the groove, the chip will not be deflected due to the tension of the first solder pastes and the second solder pastes, so that a chip packaging structure meets the expected requirements. The chip packaging structure is further provided in the present disclosure.

